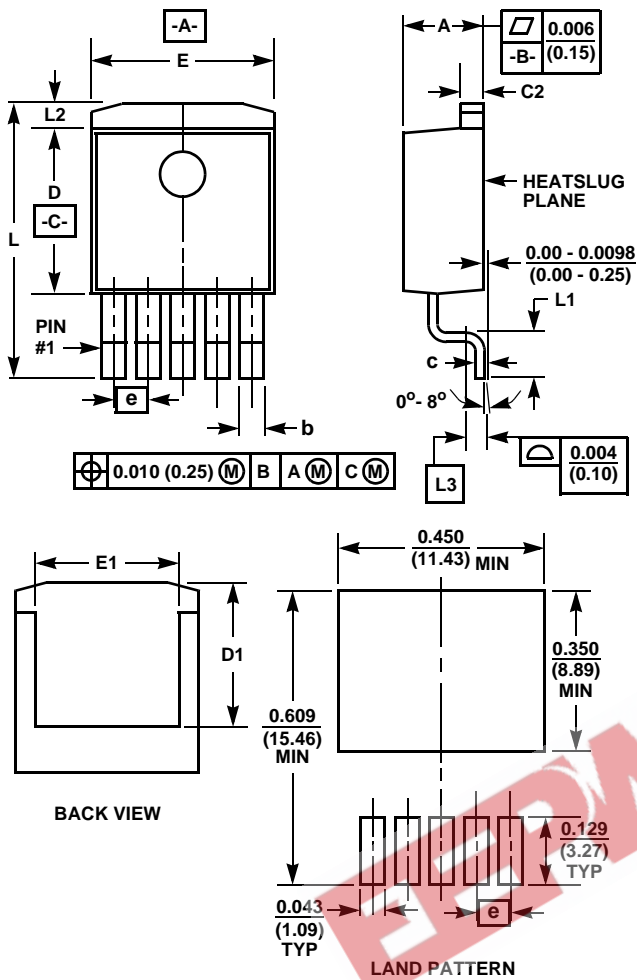


Plastic Packages for Integrated Circuits

Single-In-Line Plastic Packages (SIP)



Z5.067A

5 LEAD PLASTIC SINGLE-IN-LINE PACKAGE SURFACE MOUNT "GULLWING" LEAD FORM

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
C2	0.048	0.055	1.22	1.39	5
D	0.350	0.370	8.89	9.39	-
E	0.395	0.405	10.04	10.28	-
D1	0.310	-	7.88	-	-
E1	0.310	-	7.88	-	-
L	0.549	0.569	13.95	14.45	-
L1	0.068	0.088	1.72	2.24	-
L2	0.045	0.055	1.15	1.40	-
L3	0.030 BSC		0.76 BSC		4
b	0.028	0.037	0.71	0.94	5, 6, 7
c	0.018	0.024	0.46	0.60	5
e	0.067 BSC		1.70 BSC		-

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NOTES:

1. These package dimensions are within allowable dimensions of JEDEC MO-169AB, Issue A.
2. Controlling dimension: Inch.
3. Dimensioning and tolerance per ANSI Y14.5M-1982.
4. Gauge plane L3 is parallel to heatslug plane.
5. Dimensions include lead finish.
6. Leads are not allowed above the datum [-B-].
7. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum "b" by more than 0.003" (0.08mm).